

## Rogers RO4360G2 material specification

Property	Typical Value [1]	Direction	Units	Condition	Test Method
Dielectric Constant, $\epsilon_r$ (Process Specification)	6.15 ± 0.15	Z		10 GHz/23°C	IPC-TM-650 2.5.5.5 (2) Clamped Stripline
				2.5 GHz/23°C	
Dissipation Factor	0.0038	Z		10 GHz/23°C	IPC-TM-650, 2.5.5.5
Thermal Conductivity	0.75		W/m/K	50°C	ASTM D-5470
Volume Resistivity	4.0 × 10 <sup>13</sup>		Ω•cm	Elevated T	IPC-TM-650, 2.5.17.1
Surface Resistivity	9.0 × 10 <sup>12</sup>		Ω	Elevated T	IPC-TM-650, 2.5.17.1
Electrical Strength	784	Z	V/mil		IPC-TM-650, 2.5.6.2
Tensile Strength	131 (19) 97 (14)	X Y	MPa (kpsi)	40 hrs 50%RH/23°C	ASTM D638
Flexural Strength	213 (31) 145 (21)	X Y	MPa (kpsi)	40 hrs 50%RH/23°C	IPC-TM-650, 2.4.4
Coefficient of Thermal Expansion	13	X	ppm/°C	-50°C to 288°C After Replicated Heat Cycle	IPC-TM-650, 2.1.4.1
	14	Y			
	28	Z			
Tg	>280		°C	N/A	ASTM D3850 using TMA
Td	407°C		°C	N/A	ASTM D3850 using TGA
T288	>30	Z	min	30 min / 125°C Prebake	IPC-TM-650 2.4.24.1
Moisture Absorption	0.08		%	50°C/48hr	IPC-TM-650 2.6.2.1 ASTM D570
Thermal Coefficient of $\epsilon_r$	-131 @ 10 GHz	Z	ppm/°C	-50°C to 150°C	IPC-TM-650, 2.5.5.5
Density	2.16		gm/cm <sup>3</sup>	RT	ASTM D792
[4] Copper Peel Strength	5.2 (0.91)		pli (N/mm)	Condition B	IPC-TM-650 2.4.8
Flammability	V-0				UL94 File QMTS2.E102763

Standard Thickness	Standard Panel Size	Standard Copper Cladding
0.008" (0.203mm), 0.012" (0.305mm) 0.016" (0.406mm), 0.020" (0.508mm) 0.024" (0.610mm), 0.032" (0.813mm), 0.060" (1.524mm)	12" X 18" (305 X 457 mm) 24" X 18" (610 X 457 mm) 48" X 36" (1.224 m X 915 mm)	½ oz. (18µm), 1 oz. (35µm) and 2 oz. (70µm) electrodeposited copper foil

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